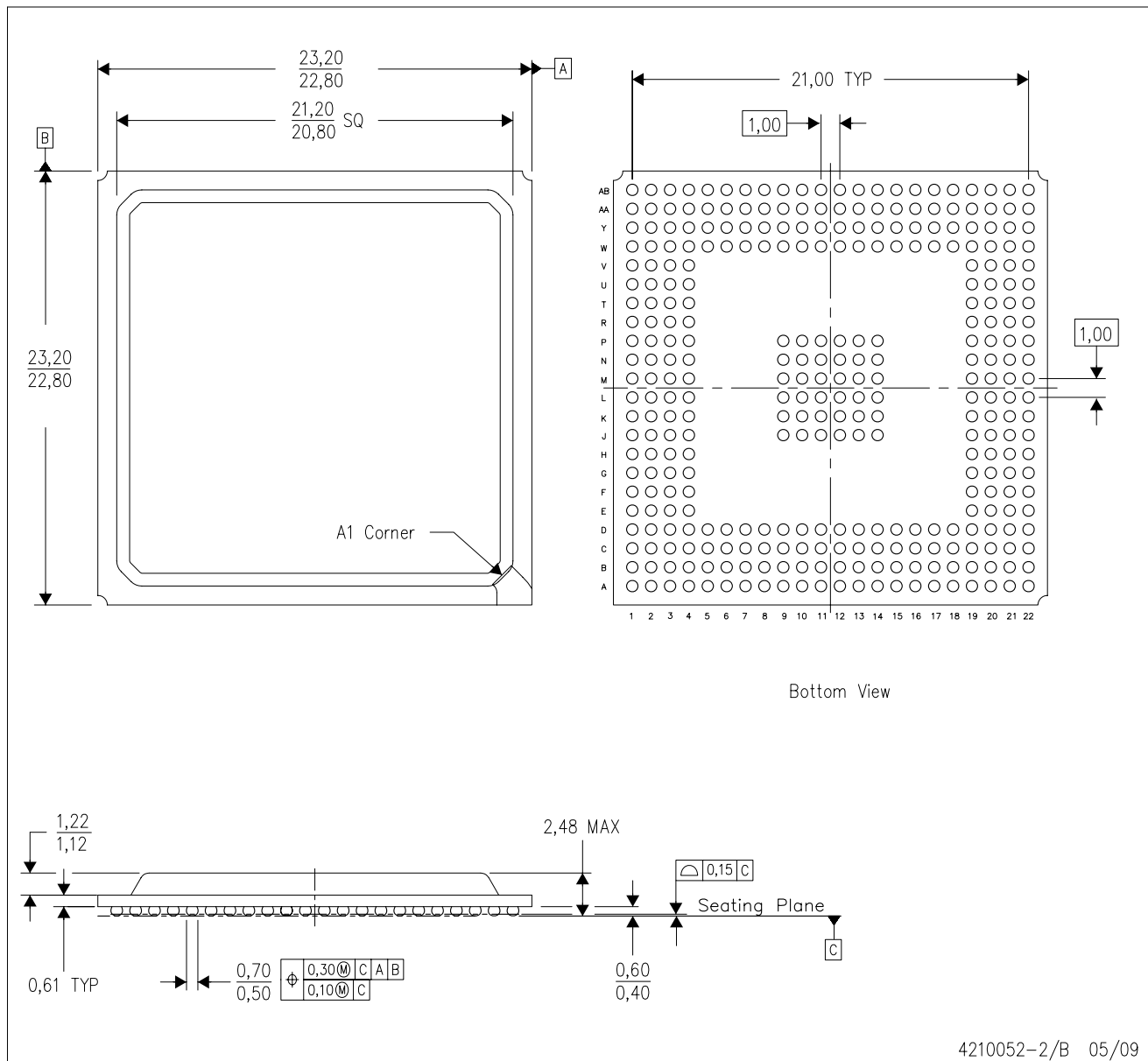


MECHANICAL DATA

ZHR (S-PBGA-N324)

PLASTIC BALL GRID ARRAY



- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - Falls within JEDEC MO-151
 - Thermally Improved BGA (TI-BGA).
 - Soldermask under die is opened
 - This is a Pb-free solder ball design.

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